



AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph at page 2, lines 7-13 with the following paragraph:

In [a] an extrusion-based modeling system, modeling material is supplied to the extrusion head as a feedstock of either a liquid or a solid material. Where the feedstock of modeling material is in solid form, a liquifier brings the feedstock to a flowable temperature for deposition. One technique is to supply modeling material in the form of a filament strand. Solid material feedstocks may alternatively be in the form of wafers, rods, slugs, or the like. A pressurization means is used to extrude molten modeling material from the extrusion head.

Please replace the paragraph at page 3, lines 7-14 with the following paragraph:

In building a model from a modeling material that thermally solidifies upon a drop in temperature, the modeling base is contained within a temperature-controlled build envelope. The build envelope is preferably a chamber which is heated to a temperature higher than the solidification temperature of the modeling material during deposition, and then gradually cooled to relieve stresses from the material. As disclosed in U.S. Patent No. 5,866,058, this approach anneals stresses out of the model while it is being built so that the finished model is stress free and has very little distortion.

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